

Customer No.: 31561
Application No.: 10/605,056
Docket No.: 9388-US-PA

IN THE CLAIMS

Please amend the claims according to the following listing of claims and substitute it for all prior versions and listings of claims in the application.

1. (currently amended) A packaging process, comprising ~~the steps of:~~

providing an insulation layer, wherein the insulation layer has an upper surface and a corresponding lower surface;

forming a plurality of openings passing through the insulation layer;

attaching a tape onto the lower surface of the insulation layer;

forming a conductive body inside the openings, wherein the conductive body has a die pad and a plurality of contacts and a formation of the conductive body is completed when the step of forming the conductive body inside the openings is concluded;

mounting a chip over the upper surface of the insulation layer, wherein the chip has an active surface, a corresponding backside and a plurality of chip contacts on the active surface and the chip is electrically connected with the conductive body by attaching the backside of the chip onto the die pad, electrically connecting the chip contacts with the contacts of the conductive body via a plurality of conductive wires, and forming a packaging material to encapsulate the chip and the conductive wires; and

removing the tape.

2. (original) The packaging process of claim 1, wherein forming the conductive body inside the openings comprises electroless plating.

Claims 3-6 (cancelled)

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7. *(original)* The packaging process of claim 1, wherein before mounting the chip over the upper surface of the insulation layer, a multi-layer substrate is formed by further conducting the steps comprising:

forming an additional insulation layer over the insulation layer;

forming a plurality of openings passing through the additional insulation layer;

and

forming an additional conductive body inside the openings of the additional insulation layer.

8. *(original)* The packaging process of claim 1, wherein before mounting the chip over the upper surface of the insulation layer, a multi-layer substrate is formed by repeating the steps comprising:

forming an additional insulation layer over the insulation layer;

forming a plurality of openings passing through the additional insulation layer;

and

forming an additional conductive body inside the openings of the additional insulation layer

9. *(original)* The packaging process of claim 1, wherein material constituting the conductive body includes copper.

10. *(original)* The packaging process of claim 1, wherein material constituting the conductive body includes gold.

11. *(original)* The packaging process of claim 1, wherein the conductive body is a composite structure comprising multiple metallic layers.

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12. *(original)* The packaging process of claim 1, wherein the conductive body is a composite structure comprising a gold layer, a palladium layer, a nickel layer and a palladium layer.

13. *(original)* The packaging process of claim 1, wherein material constituting the insulation layer is selected from a group consisting of glass epoxy resin, Bismaleimide-Triazine, polyimide and epoxy resin.

Claims 11-18 (cancelled)